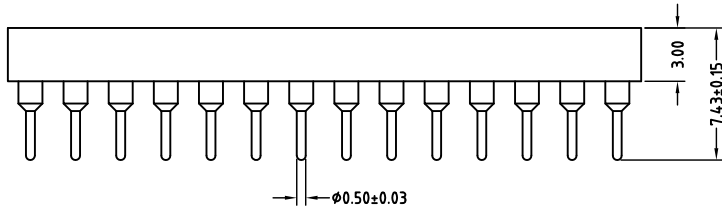
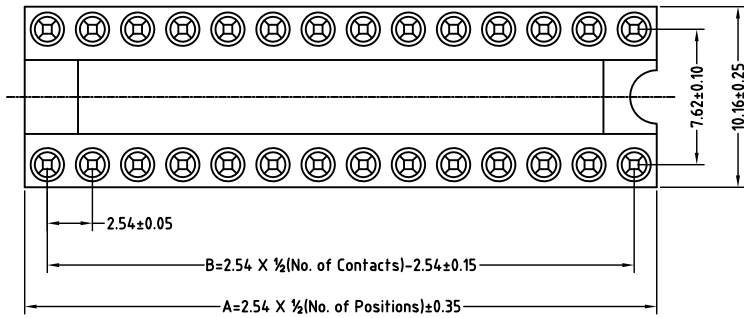
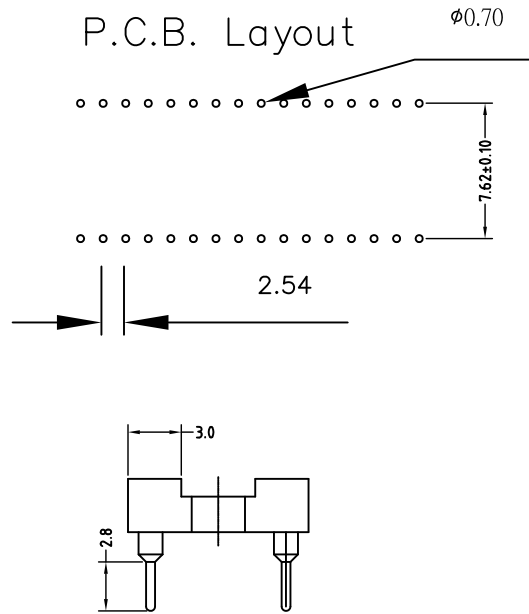


Technical Data

P.C.B. Layout



Material:

Pin(outer sleeve): Brass,machined CuZn38Pb2
 Clip(contact 4 finger): Beryllium Copper,Phosphor Bronze heat treated
 Plating(outer sleeve):
 Tin plated:2um/80u" Ni, 5um/200u" Sn
 Gold Plated:2um/80u" Ni,Full gold
 Plating(contact): 2um/80u" Ni, gold or Tin plated
 Insulator(black): Glass filled thermoplastic polyester UL94V-0

Electrical:

Current rating: 3Amps/contact max.
 Contact resistance: $\leq 4m\Omega$ /contact
 Insulation resistance: $\geq 1000M\Omega$ at V=100V
 Operating voltage: 60VAC/DC

Mechanical:

Average insertion force with steel pin of $\phi 0.43mm/0.17"$: <250g
 Average withdrawal force with steel pin of $\phi 0.43mm/0.17"$: >50g min.
 Mechanical life cycle:min.200
 Operating temperatures: Gold Plated:-55°C to+105°C
 Tin plated:-40°C to+105°C
 Soldering temperature: +260°C,10s max.

How To Order

RI— (1)(2)/(3) — (4)/(5)

- (1) No. of contact (2) P : Plug S : Socket
 (3) 1 : Single Row/2 : Double Row/3 : 0.3" Row to Row Pitch/
 4 : 0.4" Row to Row Pitch/6 : 0.6" Row to Row Pitch
 (4) Contact Plating
 GF : Gold Flash/T200 : Tin200 μ "/SG : Select Gold Flash/
 S10 : Select Gold plated 10 μ "/S15 : Select Gold plated
 15 μ "/S30 : Select Gold plated 30 μ "
 (5) Blanked : Dip Solder Type/W : Wire Wrapping/D : SMD Type
 E : Empty , No Bar
 Ex. RI—08S/3—SG
 Round IC Socket 8Pin , Socket/0.3" Row to Row Pitch ,
 Select Gold Flash
 Ex. RI—18S/3—SG
 Round IC Socket 18Pin , Socket/0.3" Row to Row Pitch , Select Gold Flash

No. of Positions	DIM"A"	DIM"B"
6	7.62	5.08
8	10.16	7.62
14	17.78	15.24
16	20.32	17.78
18	22.86	20.32
20	25.40	22.86
24	30.48	27.94
28	35.56	33.02

				TOLERANCES ARE		APPROVED		DATE		DRAWING NO	
				X.	±0.25	CHECKED		DATE		NAME	
				X.X	±0.1	DRAWN		DATE		UNIT	
				X.XX	±0.01	Lee		2006/06/02		MM	
				X.XXX	±0.005	SER		REVISIONS		SCALE	
				X.XXXX	±0.002	Lee		2006/06/02		1:1	
				△	新圖發行	CHK		DATE		REV	
						Lee		2006-06-02		A	